

CSP Top view LEDs

CSP0603AN101-WP26220453001-3T

**Features**

- Dimension: 0.6*0.3*0.15 mm LED
- Direct attach-Flip Chip type
- Wide viewing angle.
- Suitable for vapor-phase reflow, Infrared reflow and wave solder processes
- Computable with automatic placement equipment.
- Available on tape and reel (8mm Tape).
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br<900ppm,Cl<900ppm,Br+Cl<1500ppm)
- Precondition: Bases on JEDEC J-STD 020D Level 3

Descriptions

- The 0603 CSP LED is much smaller than general components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.

Applications

- Status indicator, keypad, keyboard, and industrial equipment.
- Light pipe application.
- General use.

Device Selection Guide

Type	Chip Materials	Emitted Color	Resin Color
W	InGaN	White	Yellowish

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Forward Current	I _F	20	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	40	mA
Power Dissipation	P _d	72	mW
Junction Temperature	T _j	115	°C
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +90	°C
ESD	ESD _{HBM}	2000	V
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	45	77	90	mcd	I _F =1mA
Viewing Angle	2θ _{1/2}	-----	150	-----	deg	I _F =1mA
Forward Voltage	V _F	2.45	2.6	3.05	V	I _F =1mA

Notes:

1. Tolerance of Luminous Intensity: ±11%
2. Tolerance of Forward Voltage: ±0.1V
3. Led components are not supposed to be reverse operated
4. Electric and optical data are reference only.

Bin Range of Luminous Intensity

Chip	Bin Code	Min.	Max.	Unit	Condition
W	A1	45	60	mcd	IF=1mA
	A	60	71		
	B	71	90		

Note:
Tolerance of Luminous Intensity: $\pm 11\%$

Bin Range of Forward Voltage

Chip	Bin Code	Min.	Max.	Unit	Condition
W	VA	2.45	2.55	V	IF=1mA
	VB	2.55	2.65		
	VC	2.65	2.75		
	VD	2.75	2.85		
	VE	2.85	2.95		
	VF	2.95	3.05		

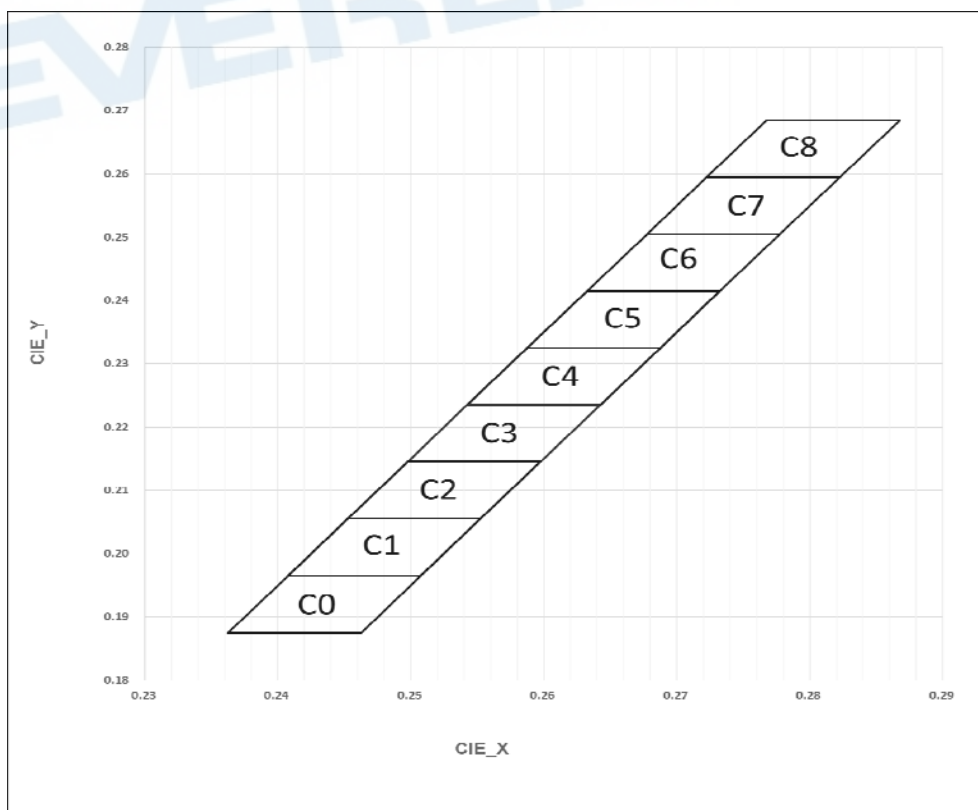
Note:
Tolerance of Forward Voltage: $\pm 0.1V$

Bin Range of Chromaticity Coordinates

Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y
C0	0.2408	0.1965	C3	0.2543	0.2235	C6	0.2678	0.2505
	0.2508	0.1965		0.2643	0.2235		0.2778	0.2505
	0.2463	0.1875		0.2598	0.2145		0.2733	0.2415
	0.2363	0.1875		0.2498	0.2145		0.2633	0.2415
C1	0.2453	0.2055	C4	0.2588	0.2325	C7	0.2723	0.2595
	0.2553	0.2055		0.2688	0.2325		0.2823	0.2595
	0.2508	0.1965		0.2643	0.2235		0.2778	0.2505
	0.2408	0.1965		0.2543	0.2235		0.2678	0.2505
C2	0.2498	0.2145	C5	0.2633	0.2415	C8	0.2768	0.2685
	0.2598	0.2145		0.2733	0.2415		0.2868	0.2685
	0.2553	0.2055		0.2688	0.2325		0.2823	0.2595
	0.2453	0.2055		0.2588	0.2325		0.2723	0.2595

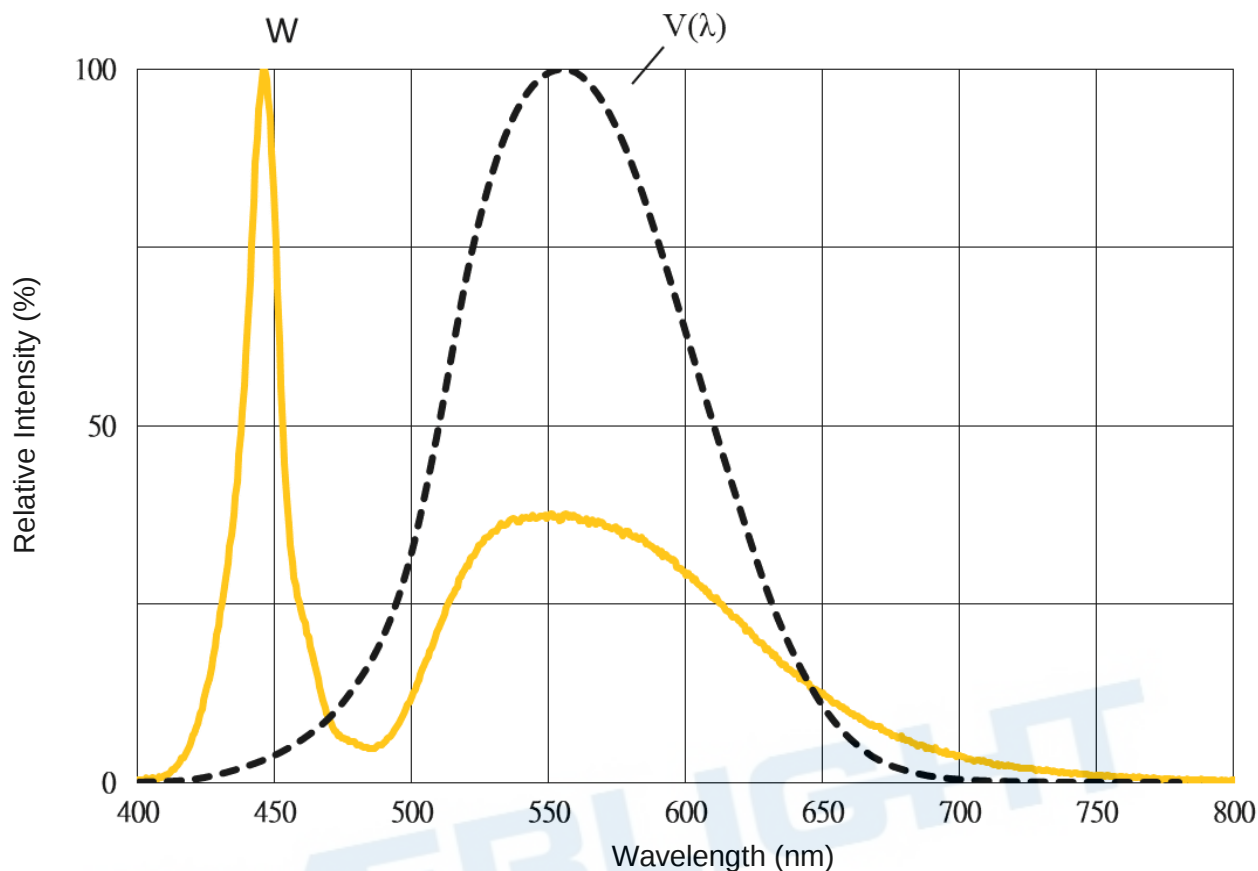
Notes: Tolerance of Chromaticity Coordinates : ± 0.01

The C.I.E. 1931 Chromaticity Diagram



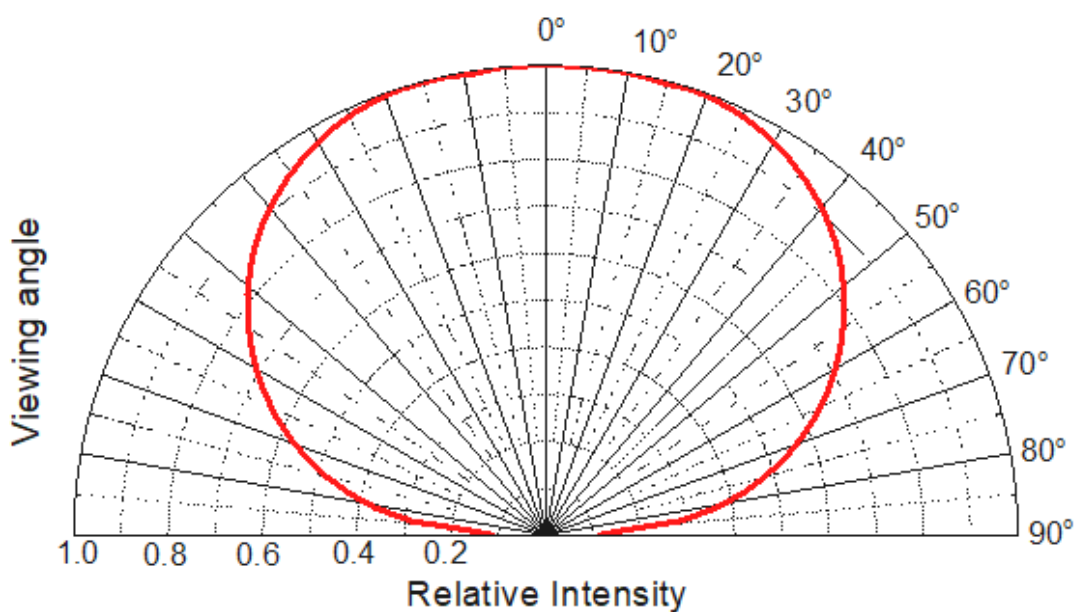
Typical Electro-Optical Characteristics Curves

Typical Curve of Spectral Distribution



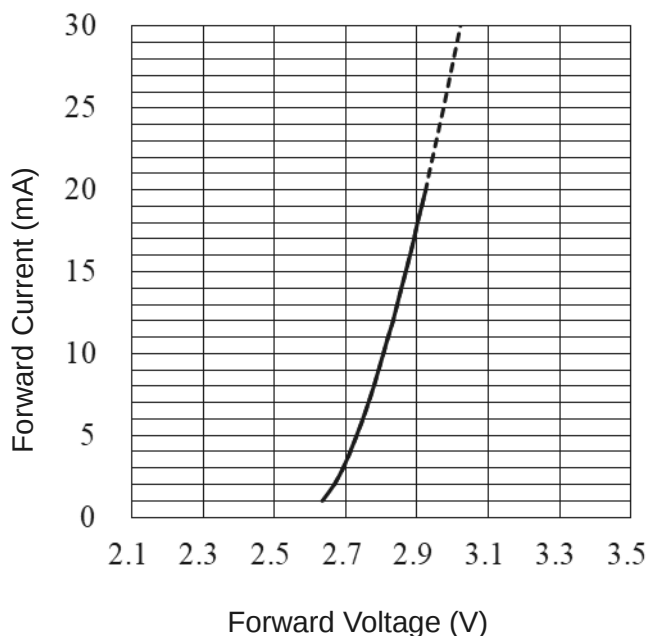
Note: $V(\lambda)$ = Standard eye response curve; $I_F = 1\text{mA}$

Diagram Characteristics of Radiation

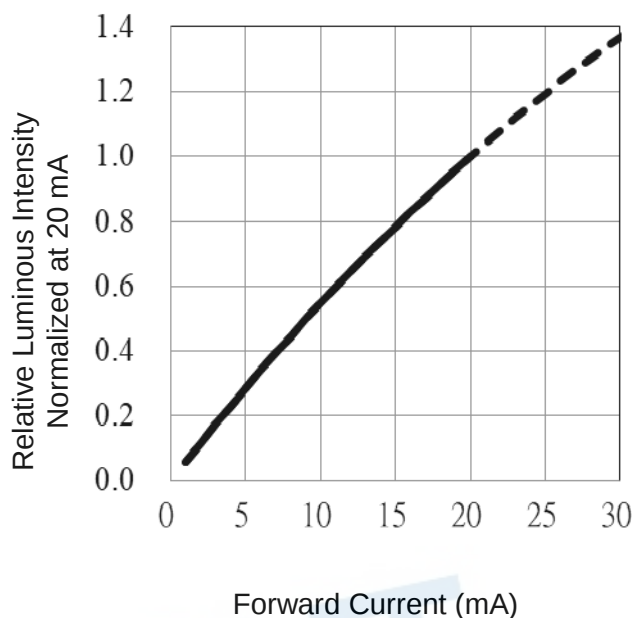


Typical Electrical-Optical Characteristics Curves (25°C Ambient Temperature)

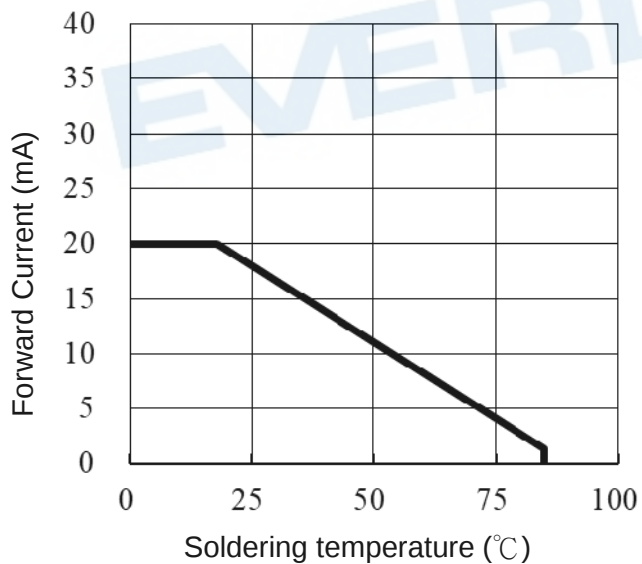
Forward Current vs. Forward Voltage



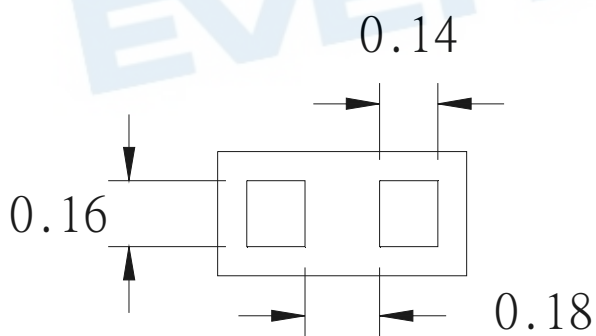
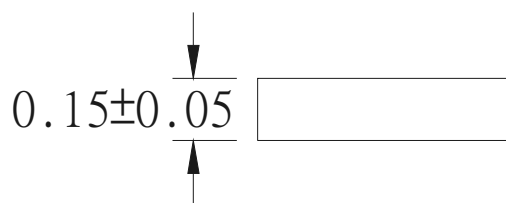
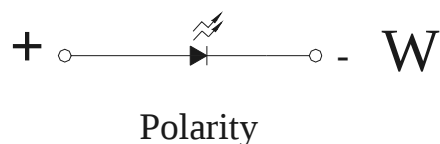
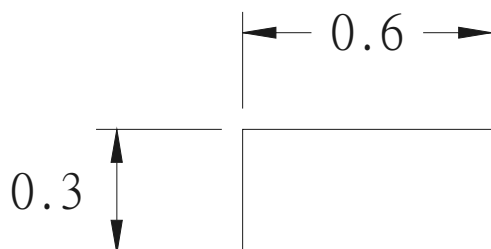
Relative Luminous Intensity vs. Forward Current



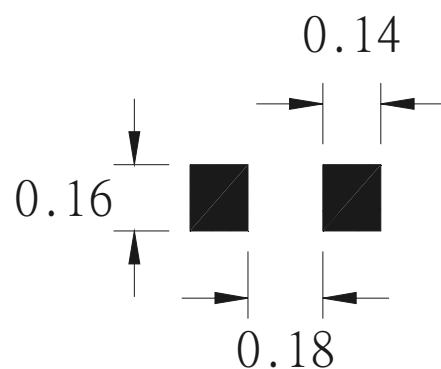
Forward Current Derating Curve



Package Dimension



Bot. view



Recommend Soldering Pattern

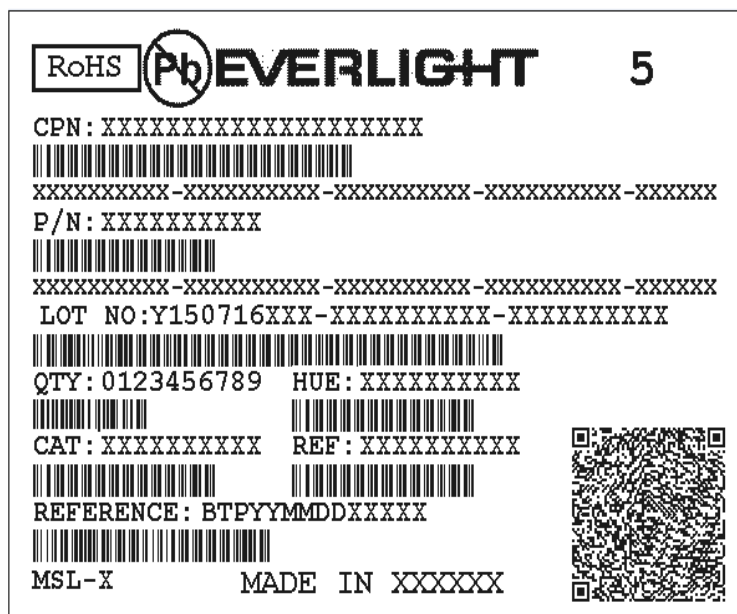
Suggested pad dimension is just reference only.
Please modify the pad dimension based on individual need.

Note:

1. Tolerances unless mentioned ± 0.05 mm. Unit = mm
2. Chip to colloid edge size is controlled to a minimum of 0.025mm

Moisture Resistant Packing Materials

Label Explanation



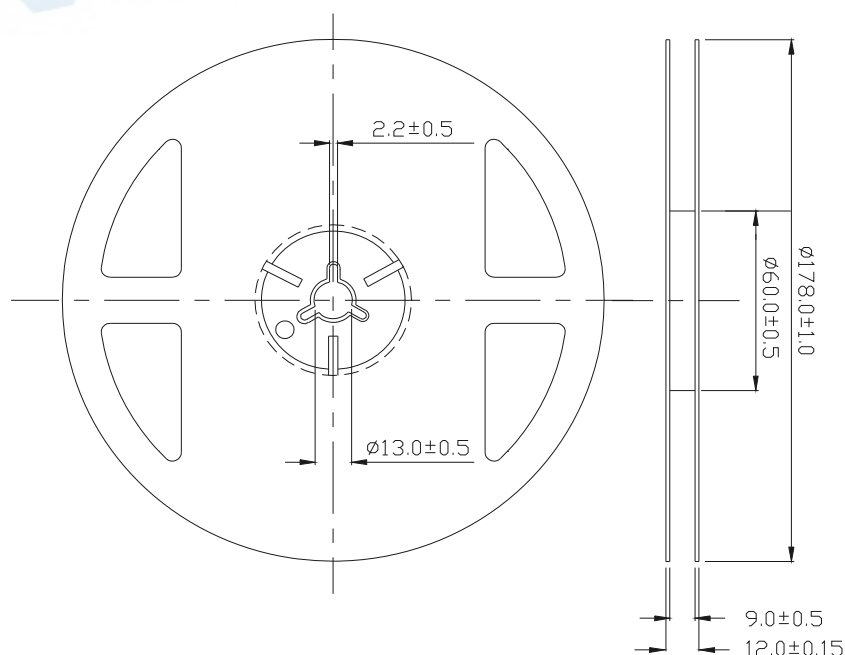
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Note:

The wavelength is marked on the label of lot number.

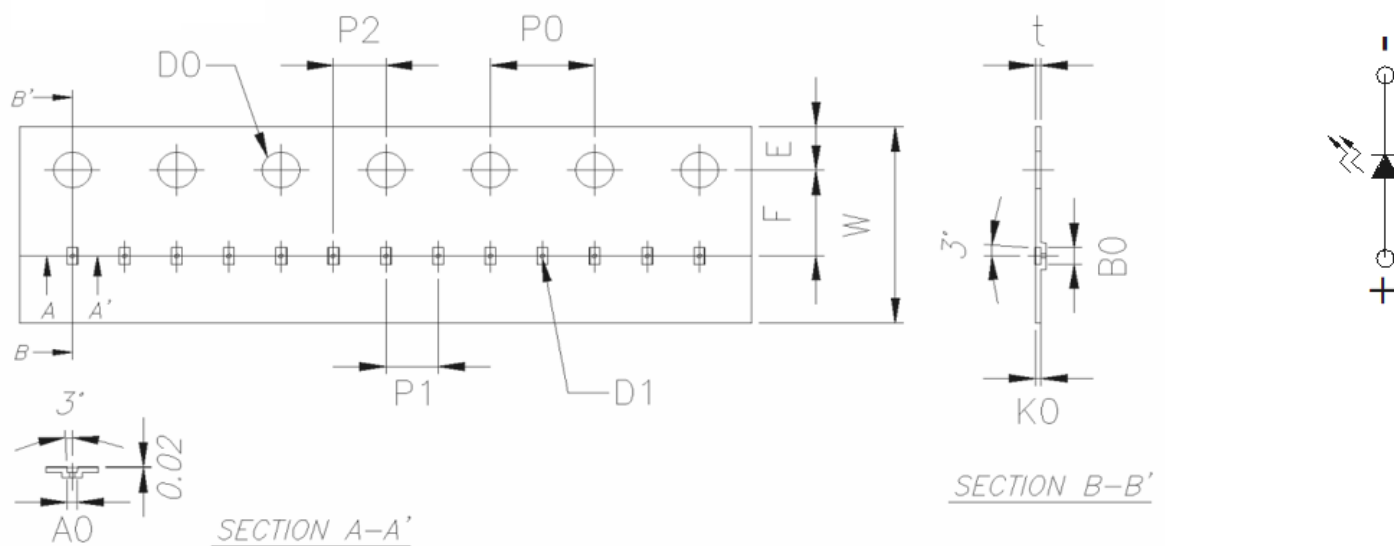
1. Long: lot number + L
2. Medium: lot number + M
3. Short: lot number + S

Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

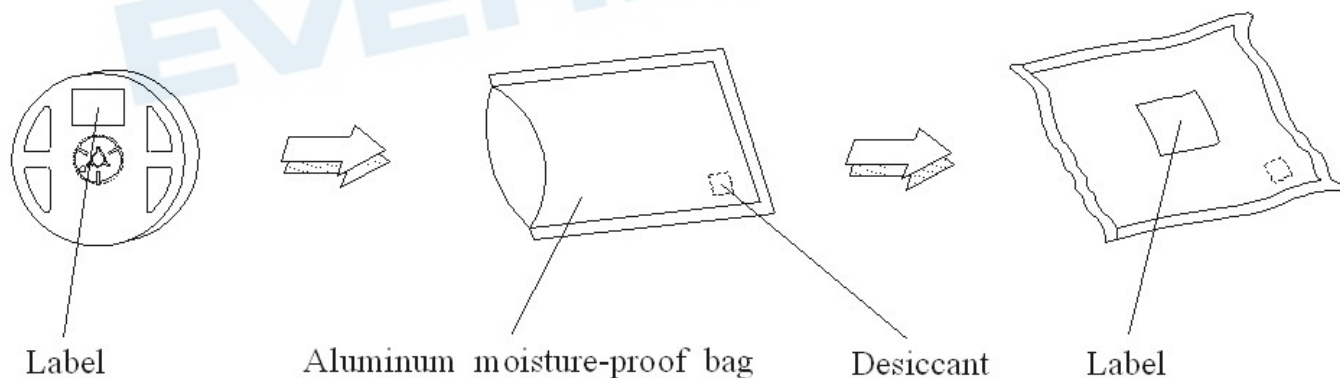
Carrier Tape Dimensions:



Notes:

1. Tolerances unless mentioned $\pm 0.1\text{mm}$. Unit = mm
2. Minimum package quantity is 250 pieces for remainders
3. All dimensions without tolerances are for reference only.

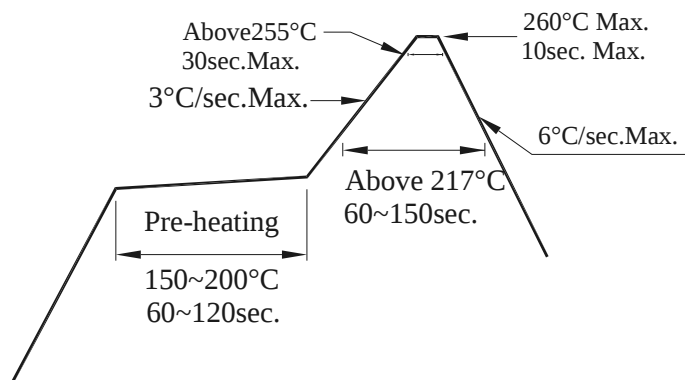
Moisture Resistant Packing Process



Precautions for Use

1. Over-current-proof

1.1 Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).



2. Storage

2.1 Moisture proof bag should only be opened immediately prior to usage.

2.2 Environment should be less than 30°C and 60% RH when moisture proof bag is opened.

2.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.

2.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile

3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

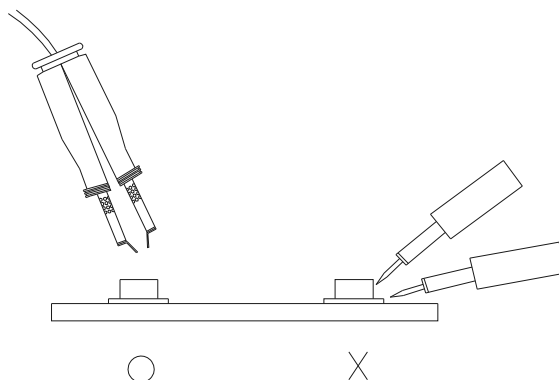
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

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2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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